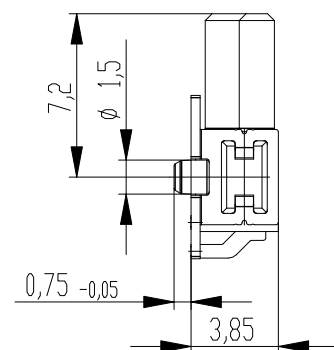
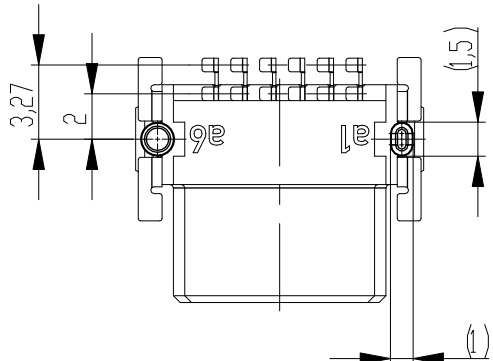
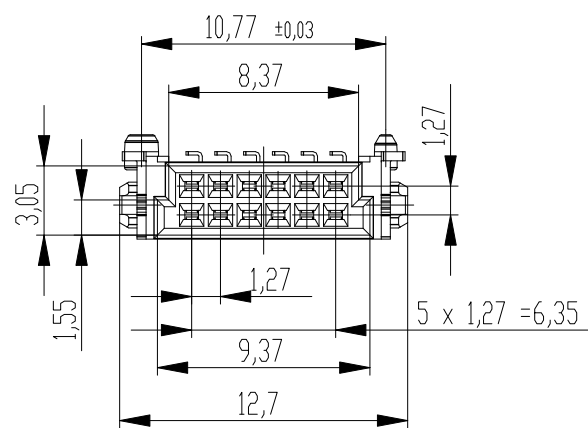
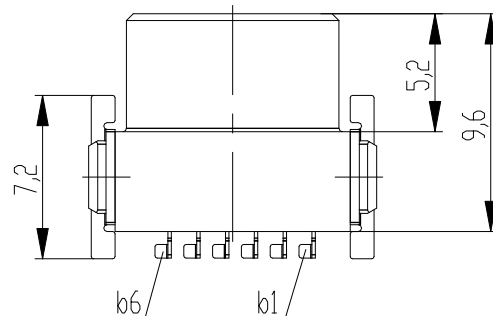
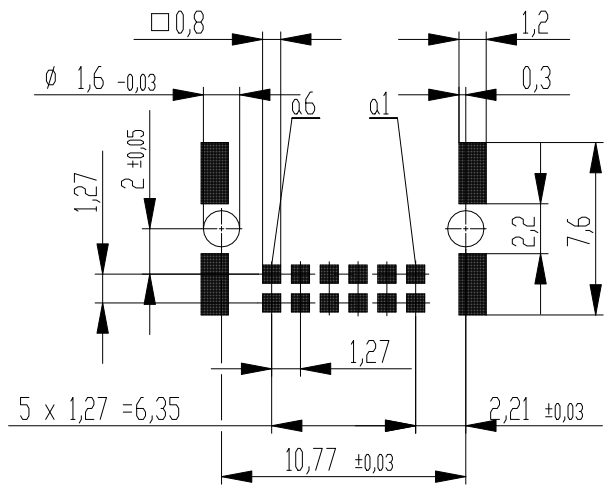
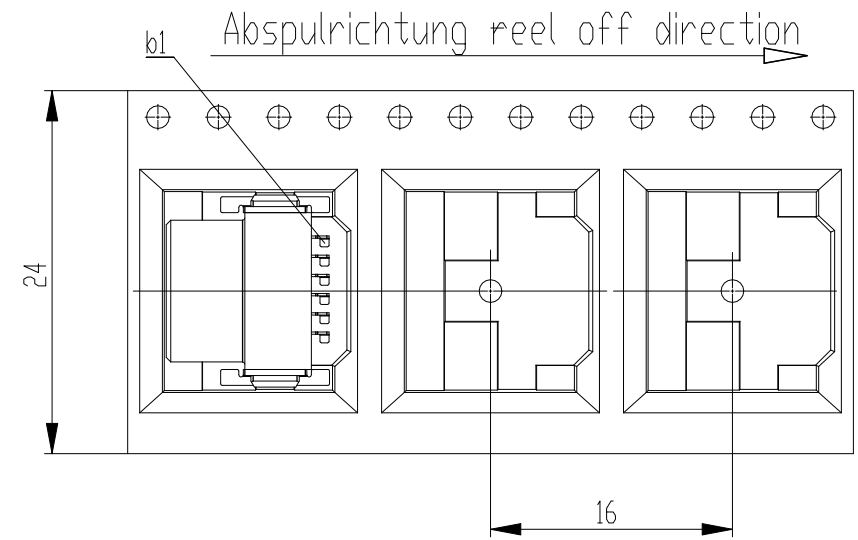
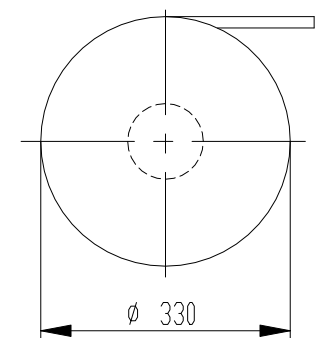


Leiterplatten-Layout Vorschlag für SMT
PCB-Layout Proposal for SMT

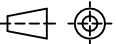


Anforderungsstufe 1
performance level 1
Kontaktbereich vergoldet
mating area gold plating
Anschlussbereich verzinnt 4-6 µm
terminal area 4-6 µm tin plating
Koplanarität der Anschlüsse ≤ 0,1 mm
coplanarity area of termination ≤ 0,1 mm

Verpackt im Gurt in Anlehnung an DIN IEC 60286-3
tape on reel packaging according to DIN IEC 60286-3
Verpackungseinheit: 560 Stück
packaging unit: 560 pcs



BA7-03 - Standard Bauhöhe
type7-03 - standard assembly height

Dimension no.				Tolerances Dim. for Information ISO 8015		 All Dimensions in mm		Scale 5:1		Material			
<u>Customer drawing:</u> THIS DRAWING IS A CONTROLLED DOCUMENT.				Subject to modification without prior notice. Drawing will not be updated.		ERNI-Federl. SMC-Q 12-SMD-BA7-03 Female SMC-Q 12-SMD-type7-03							
g		04.02.2020				©=154740-E						I	
Index		Date										A3	
								Class				SMCQ	

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The German version of this drawing has been offered for convenience only
and may deviate from the English original.
In case of any deviation the English version shall prevail.